

IBM-POU920020057US2 Examiner L. Z. Tsukerman,
10/775,922 - 2 -

IBM

C: Amendments to The Claims:

What is claimed is:

1 1. (Previously Submitted) Land Grid Array structure
2 comprising,
3 a flex film interposer for providing a Land Grid Array (LGA)
4 electrical connection disposed between a Multi-Chip Module
5 (MCM) and the next level of integration of a Land Grid Array
6 system and said flex film, wherein said interposer also
7 provides means integral to said flex film interposer for
8 implementing a desired Engineering Change (EC) and said flex
9 film interposer also integrally provides means for
10 decoupling power to ground in the Land Grid Array structure
11 to minimize switching activity effects on the Land Grid
12 Array system when mounted on a system board.

2. (Cancelled)

3. (Cancelled)

1 4. (Currently Amended) A Land Grid Array structure according
2 to claim 1 wherein said flex film interposer has a plated
3 through hole formed therethrough and there is an insulator
4 plug composed of two parts, a plug body and a fuzz button
5 rivit expansion pin of said plug body inserted in said hole
6 to insulate the plated through hole to prevent electrical
contact of said plated through hole with ~~from~~ the system
board.